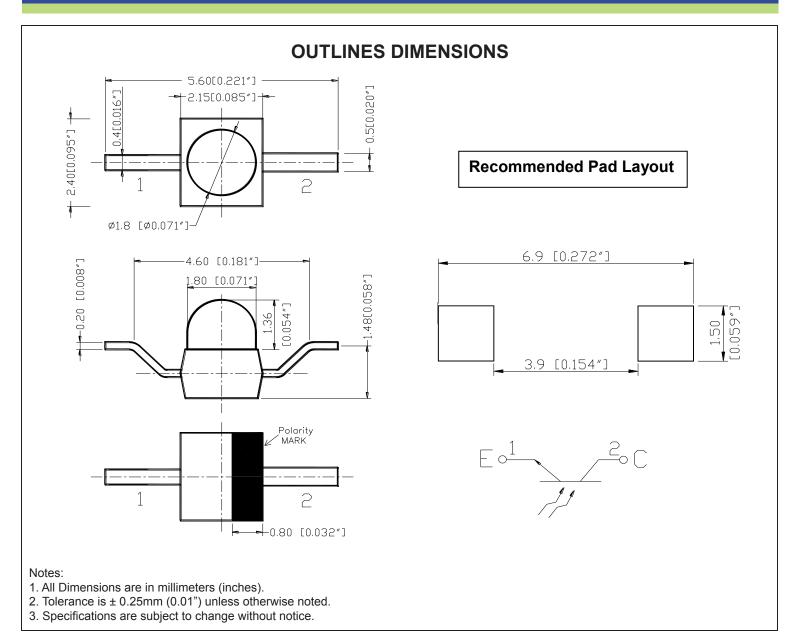


SPECIFICATIONS CSM28PTBZ



Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CSM28PTBZ	Silicon	Phototransistor	Black	15°



ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com



ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit
Power Dissipation	PD	100	mW
Collector-Emitter Voltage	VCEO	30	V
Emitter-Collector Voltage	VECO	5	V
Operating Temperature Range	Topr	-40~+80	°C
Storage Temperature Range	Тѕтс	-40~+85	°C

IFP = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Jorameter	Cymphol	Toot Condition	Value			l lmi4
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Collector-Emitter Voltage	V _{(BR) CEO}	Ic = 100μA I _B = 0	30	-	-	V
Emitter-Collector Voltage	V _{(BR) ECO}	IE = 100μA IB = 0	5	-	-	V
Collector-Emitter Saturation Voltage	V _{CE (SAT)}	Ic = 2mA I _B = 100μA	-	-	0.3	V
Rise Time	Tr	V _{CE} = 5V Ic = 1mA	-	15	-	μS
Fall Time	TF	RL = 1000Ω F = 100Hz	-	15	-	μS
Collector Dark Current	Iceo	V _{CE} = 20V Ee = 0mW/cm ²	-	-	100	nA
On State Collector Current	 (on)	V_{CE} = 5V, D=6mm P_{D} = 0.5mW λ = 940nm I_{LED} = 20mA	1.0	2.0	-	mA

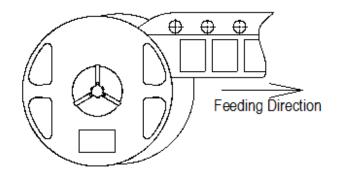


ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com

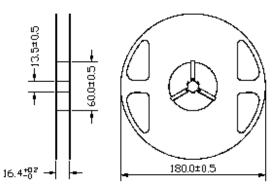


PACKAGING SPECIFICATION

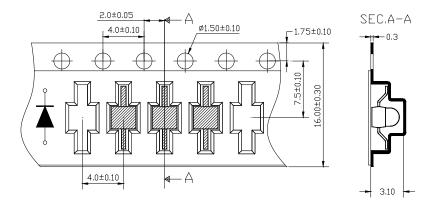
Feeding Direction



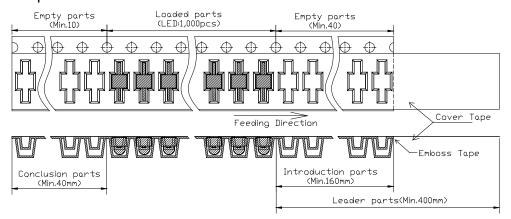
Dimensions of Reel (Unit: mm)



Dimensions of Tape (Unit: mm)



Arrangement of Tape



Notes:

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamp is two;
- 3. The cathode is oriented towards the tape sprocket hole;
- 4. 1,000 pcs/Reel



ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com



SOLDERING CONDITIONS – LAMP TYPE LED

- * Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- * Recommended soldering conditions

Dip Soldering			
Pre-Heat	100 °C Max		
Pre-Heat Time	60 Second Max		
Solder Bath Temperature	260 °C Max		
Dippng Time	5 Second Max		
Dipping Position	No lower than 3mm from the base of the epoxy		

Hand Soldering				
	3mm Series	Others		
Tomporature Soldering Time	300 °C Max	350 °C Max		
Temperature Soldering Time Position	3 Second Max	3 Second Max		
	No closer than 3mm from the	No closer than 3mm from the		
	base of the epoxy	base of the epoxy		

- * Do not apply any stress to the lead. Particularly when heated.
- * The LED must not be repositioned after soldering.
- * After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- * Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- * When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- * Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.

